Taiwan Semiconductor

1A, 200V - 1000V Surface Mount Rectifier

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Low profile package
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters in computer, automotive and telecommunication

MECHANICAL DATA

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Mattle tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.027 g (approximately)

KEY PARAMETERS				
PARAMETER VALUE UNIT				
I _{F(AV)}	1	А		
V _{RRM}	200 - 1000	V		
I _{FSM}	30	А		
T _{J MAX}	150	°C		
Package	SOD-128			
Configuration	Single die			





SOD-128

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)							
PARAMETER	SYMBOL	S1DFS	S1GFS	S1JFS	S1KFS	S1MFS	UNIT
Marking code on the device		S1DFS	S1GFS	S1JFS	S1KFS	S1MFS	
Repetitive peak reverse voltage	V _{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value	V _{R(RMS)}	140	280	420	560	700	V
Forward current	I _{F(AV)}	1		А			
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I _{FSM}	30		A			
Junction temperature	TJ	- 55 to +150		°C			
Storage temperature	T _{STG}	rg - 55 to +150		°C			





THERMAL PERFORMANCE					
PARAMETER	SYMBOL	ТҮР	UNIT		
Junction-to-lead thermal resistance per diode	R _{ƏJL}	29	°C/W		
Junction-to-ambient thermal resistance per diode	R _{eja}	82	°C/W		
Junction-to-case thermal resistance per diode	R _{eJC}	30	°C/W		

Thermal Performance Note: Units mounted on recommended PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage per diode ⁽¹⁾	$I_F = 0.5A, T_J = 25^{\circ}C$	V _F	0.91	1.0	V
	$I_F = 1.0A, T_J = 25^{\circ}C$		0.99	1.1	V
	$I_F = 0.5A, T_J = 125^{\circ}C$		0.78	0.87	V
	$I_F = 1.0A, T_J = 125^{\circ}C$		0.85	0.95	V
Deverse eurrent @ roted \/ per diade ⁽²⁾	T _J = 25°C		-	1	μA
Reverse current @ rated V_R per diode ⁽²⁾	T _J = 125°C	I _R	-	50	μA
Junction capacitance	1 MHz, V _R =4.0V	CJ	9	-	pF

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION

PART NO.	PART NO. SUFFIX(*)	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
S1xFS	Н	MW	0	SOD-128	3,500 / 7" Plastic reel	
(Note 1, 2)		MX	G	SOD-128	14,000 / 13" Plastic reel	

Notes:

- 1. "xx" defines voltage from 200V (S1DFS) to 1000V (S1MFS)
- 2. Whole series with green compound (halogen-free)
- *: Optional available

EXAMPLE P/N					
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING Code	PACKING CODE SUFFIX	DESCRIPTION
S1DFSHMWG	S1DFS	Н	MW	G	AEC-Q101 qualified Green compound



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

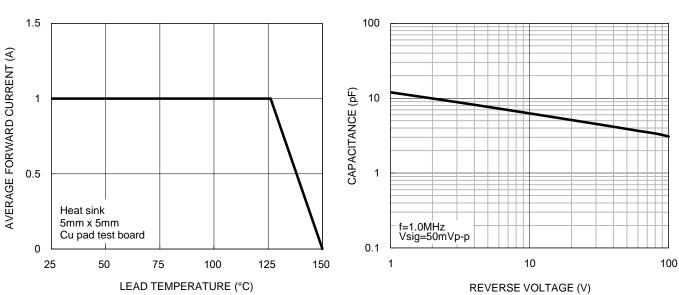
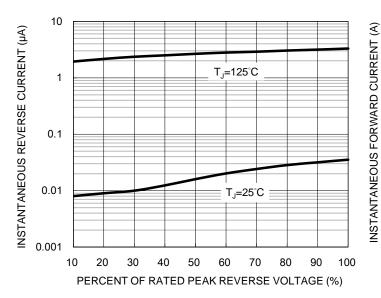


Fig.1 Forward Current Derating Curve

Fig.2 Typical Junction Capacitance

Fig.3 Typical Reverse Characteristics

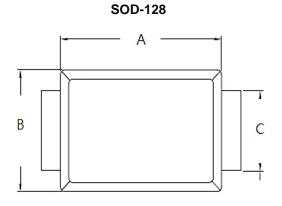




10 T_J=125°C 1 TJ=25℃ Pulse width 300µs 1% duty cycle 0.1 0.6 0.8 0.9 1 0.7 1.1 1.2 1.3 1.4 1.5 1.6 FORWARD VOLTAGE (V)

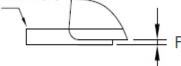


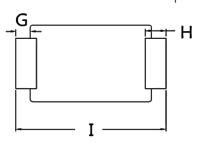
PACKAGE OUTLINE DIMENSIONS



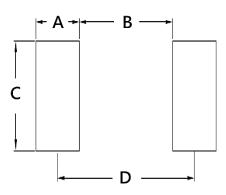


BURR SIDE (Z)





SUGGESTED PAD LAYOUT



DIM Unit (mm) Unit (inch) А 1.40 0.055 В 3.00 0.118 С 2.10 0.082 D 4.40 0.173

MARKING DIAGRAM



DIM	Unit	(mm)	Unit (inch)		
DIN	Min	Max	Min	Max	
Α	3.60	4.00	0.142	0.157	
В	2.30	2.70	0.091	0.106	
С	1.60	1.90	0.063	0.075	
D	0.90	1.10	0.035	0.043	
E	0.10	0.22	0.004	0.009	
F	0.00	0.10	0.000	0.004	
G	0.30	0.60	0.012	0.024	
Н	0.40	0.80	0.016	0.031	
I	4.40	5.00	0.173	0.197	

P/N	= Marking Code
YW	= Date Code
F	= Factory Code



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